

RELIABILITY REPORT FOR MAX9503GEEE+ PLASTIC ENCAPSULATED DEVICES

December 22, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR. SUNNYVALE, CA 94086

Approved by Sokhom Chum Quality Assurance Reliability Engineer



Conclusion

The MAX9503GEEE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX9503 filters and amplifies standard-definition video signals. Maxim's DirectDrive technology eliminates large output-coupling capacitors and sets the video black level to ground. The input of the MAX9503 can be directly connected to the output of a video digital-to-analog converter (DAC). The MAX9503 provides a compact, integrated, and low-power solution. An internal reconstruction filter smoothes the steps and reduces the spikes on the video signal from the DAC. The reconstruction filter typically has 3dB attenuation at 9MHz and 50dB attenuation at 27MHz, and ±1dB passband flatness to 5.5MHz. Maxim's DirectDrive uses an integrated charge pump and a linear regulator to create a clean negative power supply to drive the sync below ground. The charge pump injects so little noise into the video output that the picture is visibly flawless. The MAX9503 is available with +6dB (MAX9503G) and +12dB (MAX9503M) gains. The device operates from a 2.7V to 3.6V single supply and features a 10nA low-power shutdown mode. The MAX9503 is offered in space-saving 16-pin QSOP and 16-pin TQFN packages and is specified over the -40°C to +85°C extended temperature range.



A. Description/Function: DirectDrive® Video Amplifier with Reconstruction Filter B. Process: C6 345688 C. Number of Device Transistors: California

Thailand

April 23, 2005

- D. Fa brication Location:
- E. Assembly Location:
- F. Date of Initial Production:

III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1666
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

IV. Die Information

Α.	Dimensions:	60 X 61 mils
В.	Passivation:	$Si_3N_4/SiO_2\;$ (Silicon nitride/ Silicon dioxide)
C.	Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D.	Backside Metallization:	None
E.	Minimum Metal Width:	0.6 microns (as drawn)
F.	Minimum Metal Spacing:	0.6 microns (as drawn)
G.	Bondpad Dimensions:	5 mil. Sq.
Н.	Isolation Dielectric:	SiO ₂
I.	Die Separation Method:	Wafer Saw



V.	Quality	Assurance	Information
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A. Quality Assurance Contacts:	Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. S ampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

 $\lambda = \underbrace{1}_{\text{MTTF}} = \underbrace{1.83}_{192 \times 4340 \times 47 \times 2}$ (Chi square value for MTTF upper limit) $\chi = 23.4 \times 10^{-9}$ $\lambda = 23.4 \times 10^{-9}$ (Chi square value for MTTF upper limit) $\chi = 23.4 \times 10^{-9}$ (Chi square value for MTTF upper limit) $\chi = 23.4 \times 10^{-9}$ (Chi square value for MTTF upper limit)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the C6 Process results in a FIT Rate of 0.43 @ 25C and 7.50 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SU1ACQ001C D/C 0513)

The VA43 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA.



Table 1 Reliability Evaluation Test Results

MAX9503GEEE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note	e 1) Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	47	0	SU1CCQ001B, D/C 0513

Note 1: Life Test Data may represent plastic DIP qualification lots.